



Design Automation

The Minutes of the DA-WG on the 14th JISC-CENELEC Information Exchange meeting







IEC TC93 (Design Automation)

SCOPE:

to enable the integration and automation of electrotechnical product design, engineering, manufacturing, and logistics support processes, and to facilitate procedures for product operation and maintenance.







IEC TC93 Organization

Chairman Osamu Karatsu (Japan)

Secretary Victor Berman (USA)

WG1: Electronical data harmonization

WG2: Component, circuit and system description languages

WG3: Reference model for electronic design interchange format

WG5: Test, validation, conformance and qualification technologies

WG6: Library of Reusable Parts for Electrotechnical Products

WG7: Testing of Electrotechnical Products

JWG11: Product description standard for printed board, printed board

assembly, and testing in XML schema

(Joint working with TC91)







Attendees of JISC-CENELEC design automation meeting

Dr. W. Wikes Germany

Dr. R. Nerke Germany

Mr. F. Andreolli Italy

Mr. M. Graham United Kingdom

Mr. M. Teigeler Germany

Dr. O. Karatsu Japan

Dr. T. Kambe Japan

Mr. M. Takahashi Japan







1. Current status of each organization

JISC

IEC/TC93 and JNC activities
by Kambe

 Common rule for exchange methodology of product technological attribute information by Mr. Takahashi

CENELEC

Library standards and existing dictionaries by Dr. Nerke

 Catalogue Exchange and Business Processes in connection with ISO 29002 by Dr. Wilkes

Q&A







2. standards of electronic catalogue data exchange

- Draft proposal of TC93/WG6 by Mr. Takahashi
- Discussions
 - The relationship with other standards
 - Mapping methodology







Next step of this meeting

- Create landscape to visualize how the effort fits into the overall catalogue data exchange efforts.
- Thus it eventually creates synergies and already existing work can be easily identified.
- Such an overview will help to
 - Attract additional resources;
 - Help to find synergies;
 - Clearly shows where already existing standards are referenced;
 - Identify already existing work and thus avoid duplicated efforts.







Next meeting candidates

- ISO TC184/SC4 meeting at UK on May 23-28, 2010.
- IEC/ SC3D WG2 meeting in Japan on June or July, 2010
- Next CENELEC/JISC meeting in Japan, 2010
- ISO TC184/SC4 meeting at Italy on October 10-15, 2010.
- IEC general meeting (TC93) at Seattle in October, 2010.

We will decide the time and place by E-mail communication.

